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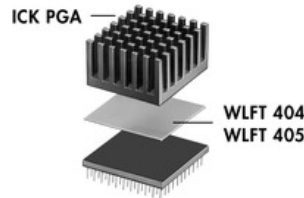
▶ Connectors f.con

Heatsinks for PGA

ICK PGA 20 x 20 x 12

51 x 51 x 12.3 mm, for IC design PGA and others

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Features [Technical Drawing](#) [Service](#) [Accessories / related products](#)

way of fixation	therm. conductive foil therm. cond. adhesive
socket	universal
suitable for processor type	universal
width	51 mm
height	12.3 mm
plate thickness	3.5 mm
length	51 mm
thermal resistance R_{th}	8 - 1.9 K/W
dissipation loss P_v	8.1 W
surface	black anodised